

FIG. 1

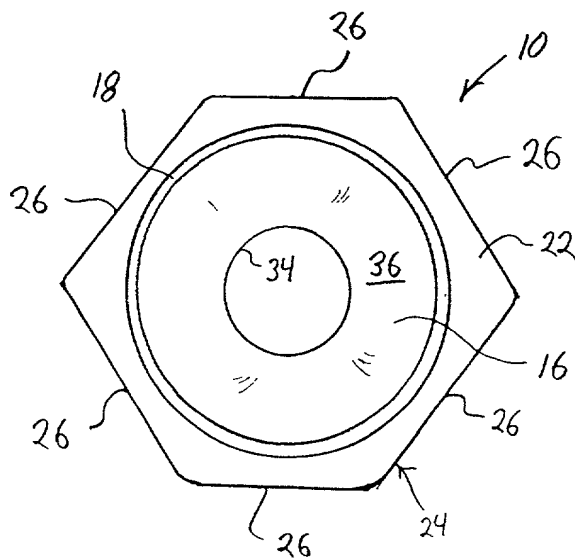
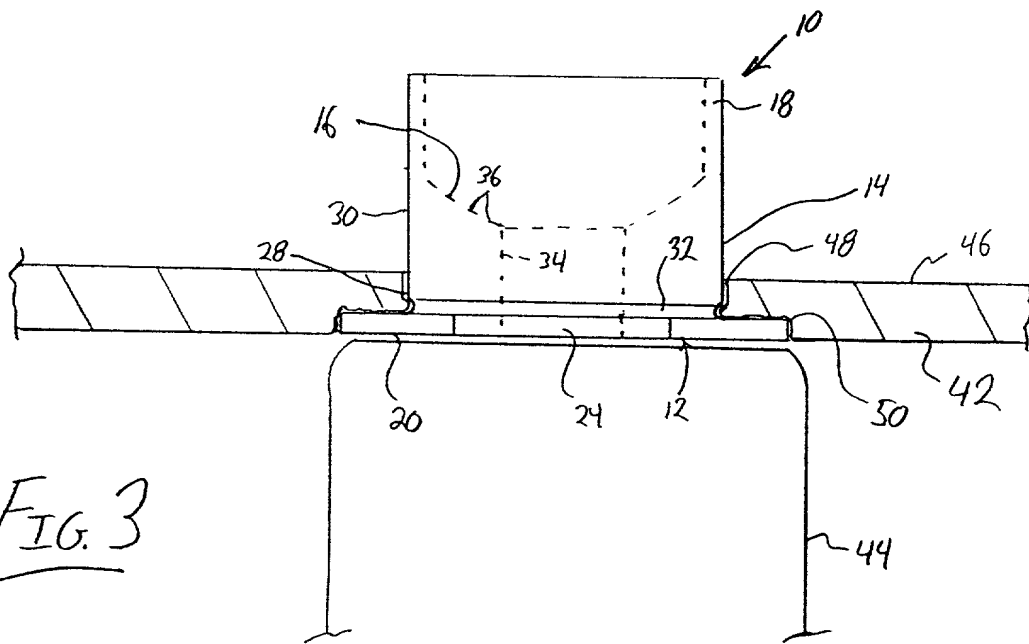
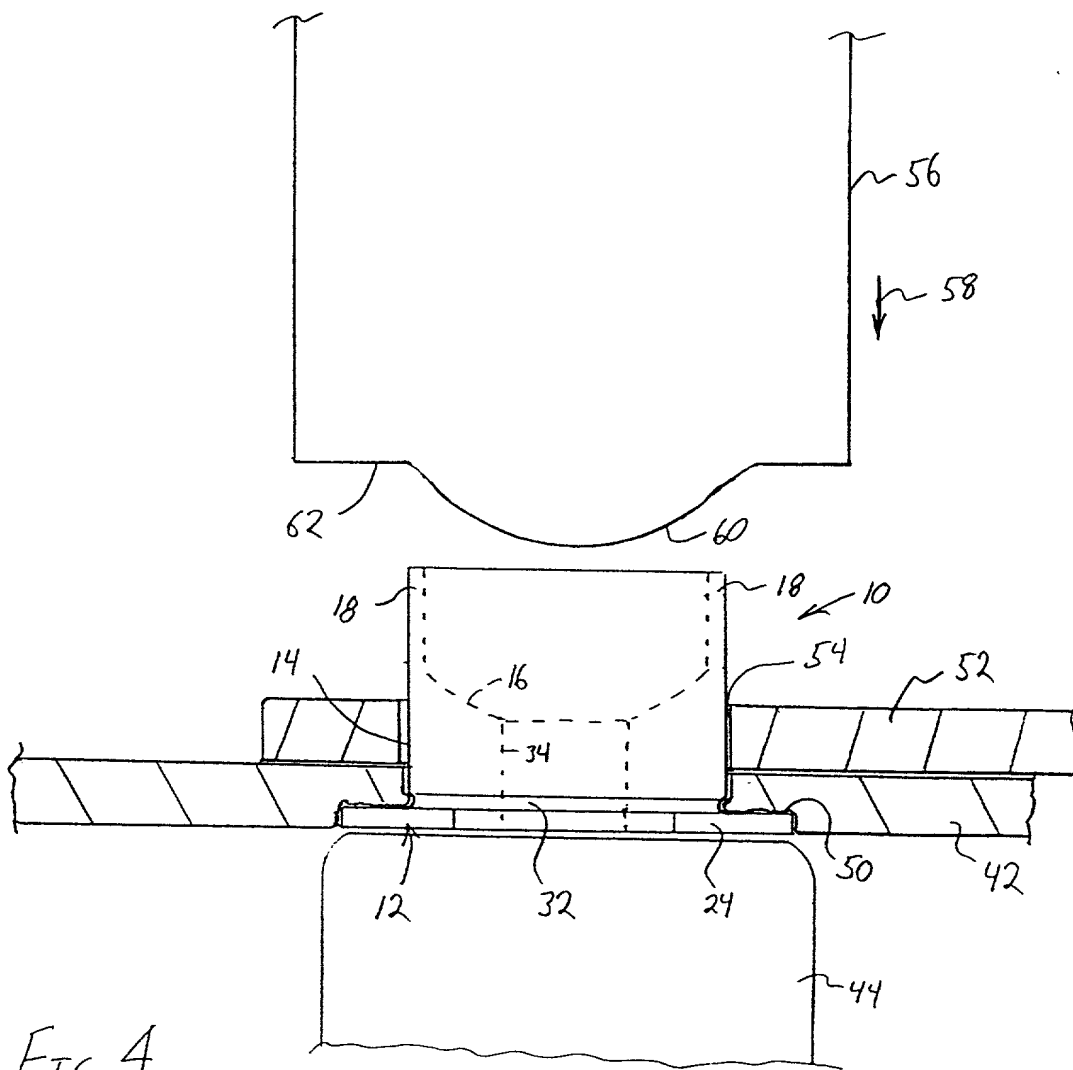


FIG. 2

FIG. 3 is a cross-sectional view of the device 10, showing the device 10 mounted on a substrate 12. The device 10 includes a base layer 14, a first conductive layer 16, a second conductive layer 18, and a third conductive layer 20. The first conductive layer 16 is disposed on the base layer 14, and the second conductive layer 18 is disposed on the first conductive layer 16. The third conductive layer 20 is disposed on the second conductive layer 18. The device 10 is connected to a power source 22 via a wire 24. The device 10 is also connected to a ground 26 via a wire 28. The device 10 is further connected to a signal source 30 via a wire 32. The device 10 is also connected to a signal source 34 via a wire 36. The device 10 is further connected to a signal source 38 via a wire 40. The device 10 is also connected to a signal source 42 via a wire 44. The device 10 is further connected to a signal source 46 via a wire 48. The device 10 is also connected to a signal source 50 via a wire 52.

FIG. 3





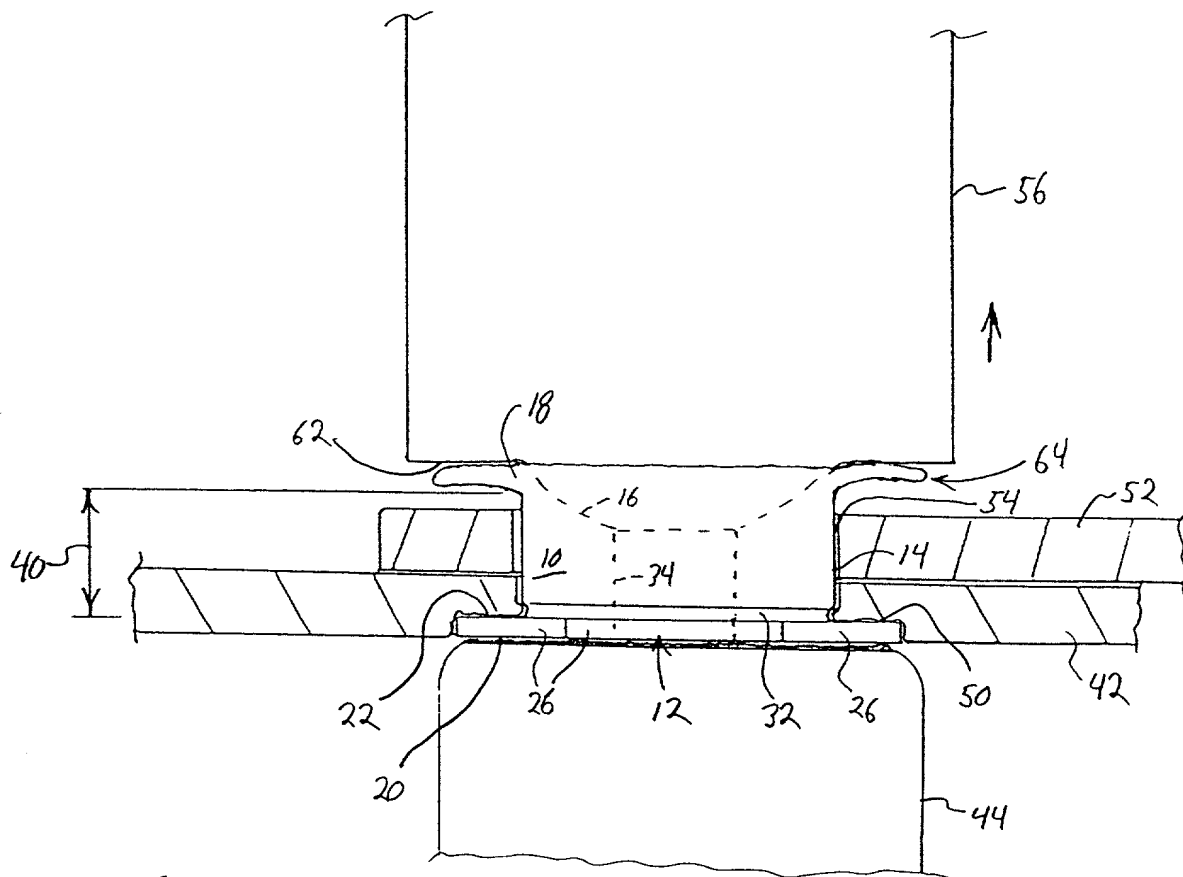


FIG. 5

